



Greeting from Chapter Chair:

Greetings to all EPS (CPMT) M'sia members. Time flies, we are approaching end of Y2017!

I am happy to announce that the CPMT Society name change to "**Electronics Packaging Society (EPS)**" has been approved by the IEEE Board of Directors and being updated in Q3 this year! We are now asking for your help and your support to realize the intended benefits of this change, as we shall embrace together with EPS HQ: improved society branding; More inclusive and better representation of the broad focus of interest of our society and improved clarity will result in increased collaboration with other IEEE societies. This is indeed a great move with good alignment with our existing technical field of interest is covering every aspect of electronic packaging. Hence, let's continue work according to the vision and mission that we have planned!



Shaw Fong Wong
IEEE CPMT M'sia
Chair 2017
Intel Technology

This year, we again have another great and exciting events. We just concluded our Bi-Annual 1-Day Technical Workshop covering the current state of art technical discussion related to WLCSP and automotive packaging. The event was well received with good engagement from >120 technical attendees that covered both Northern and Central region of M'sia. The "Best Engineering Student Award" (BESA) program is progressing very well, we have total 5 top-notch engineering faculties from 5 local universities that being selected to participate in this prestigious award. You can refer to the detail update in this 2H newsletter update. Besides, we did participate in some Academia related activities like CREST's Semiconductor & Optoelectronics Cluster Bootcamp. This helps us to continue explore the opportunity to engage with our current engineering student with more potential collaborations to join the electronic and packaging industry once they have graduated. As promised, we also continue our reach out opportunities by delivering a few invited talks at the Regional EPS related Conferences (China, Japan and Taiwan) for continue technical knowledge exchange as well as cross chapters' engagements.

Also, we are in middle of executing our long-awaited long royal membership reward program, we learnt that we have many high royalty members that continue stayed with our chapter for >10 years! Last but not least, the existing chapter's website update is also work in progress, it will be rolled up together with the next year IEMT2018, our flagship conference that will be organized by Sept, 2018.

I strongly believe we can maintaining the good linkage with our long-time established friendship beside the technical knowledge exchange. Have fun, I wish you have a great Y2017 and looking forward Y2018! Last but not least, I wish to thank all the great voluntary supports from the Y2017 Excom too!



[The change of name from IEEE CPMT to IEEE EPS](#)

(compiled by Dr Banu Poobalan)

We are pleased to announce that IEEE Components Packaging Manufacturing and Technology has been officially changed to IEEE Electronics Packaging Society (EPS). The new emblem for the EPS as below:

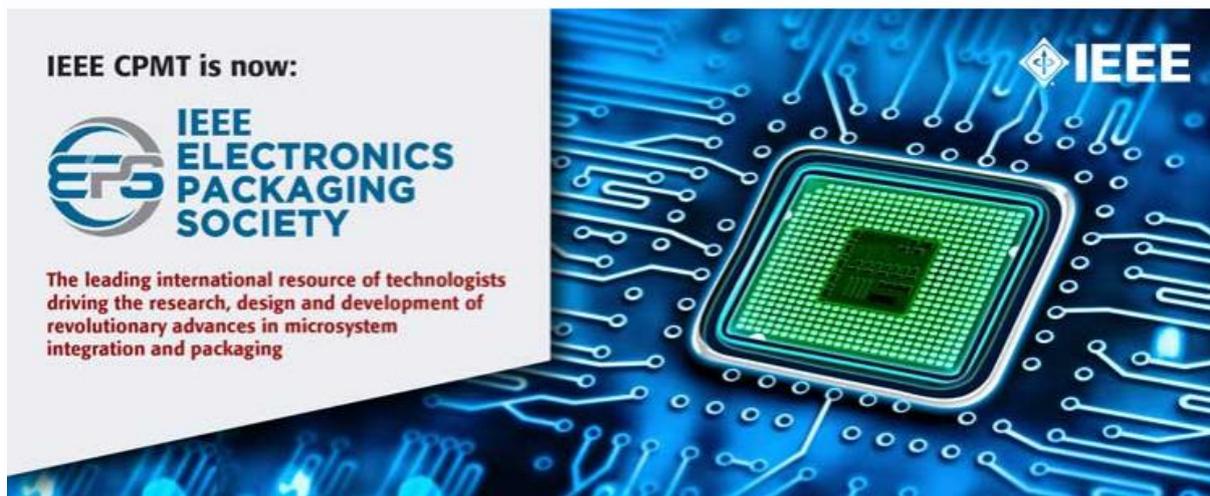


Figure 1: New outlook of IEEE EPS

For more details, kindly visit:

<http://www.businesswire.com/news/home/20170912005472/en>

[IEEE CPMT Best Engineering Student Award \(BESA\) by IEEE Component Packaging and Manufacturing Technology \(CPMT\)](#)

(Compiled by Dr. Siow Kim Shyong)

On 25th July 2017, Dr. Siow Kim Shyong, on behalf of the IEEE Component Packaging and Manufacturing Technology (CPMT) presented the IEEE CPMT Best Engineering Student Award (BESA) to Mr. Chong Hor Kong, a graduate from Department of Electrical and Electronic Engineering, Faculty of Engineering, University of Nottingham Malaysia Campus. The Award comprising a book prize worth RM 3000 and a book on electronic engineering were presented in conjunction with the 2017 University Graduation Ceremony at the University of Nottingham Malaysia Campus.

Hor Kong has the following to say, "I am sincerely honored and humbled to be the recipient of the Institute of Electrical and Electronic Engineering (IEEE) Component Packaging and Manufacturing Technology (CPMT) Book Prize. I would like to thank the selection panel and IEEE for this award, and would like to express my gratitude to The Department of Electrical and Electronic Engineering, Faculty of Engineering, University of Nottingham Malaysia Campus for my nomination. The title of my Final Year Project was "Autonomous Barcode Scanner System" under the supervision of Dr Belle Ooi. My heartfelt thanks and appreciation goes to her, for her surmountable

guidance and dedication. You have been a great supervisor/mentor and has made my educational journey inspirational and worthwhile. It was indeed challenging to juggle between projects, studies and having a "life". This journey in particular taught me to manage both the fear of failure and desire for success. Thank you again for this prestigious award."



Figure 2: The award presentation ceremony

[CREST 2017 Semiconductor & Optoelectronics Cluster Bootcamp \(10th to 12th Aug 2017\) Summary](#)

(Compiled by Prof. Cheong Kuan Yew and Shaw Fong Wong)

IEEE/EPS (CPMT) M'sia chapter was invited to engage in the Collaborative Research in Engineering, Science & Technology (CREST) Semiconductor & Optoelectronics Cluster Bootcamp that was held at SAINS@USM on 10th to 12th Aug 2017. The IEEE/EPS engaged events began with JS Sim (Infineon Technologies, Kulim) hosted a batch of 38 students for an onsite Infineon factory visit. 5 of luckier students were allowed to further visit to the clean room fab facility while the rest had dialogue-chat sessions with experienced engineers on electronic industry life and experience sharing. Overall, the participants gotten a better idea of the needs of industry and what they need to do (on top of their academic performance) to prepare for good and challenging working life.

The IEEE/EPS engaged event continue with a special dialogue session "Researchers@Work" on 11th Aug evening. Shaw Fong Wong (from EPS) together with 2 young engineers from Intel Technology conducted an experience sharing as well as motivation discussion with approximately 90+ undergraduates. The sharing topics including their past industry life as well as the learning curves while starting to engage as a researcher (R&D) working environment. The sharing session was well received and there were many good questions discussed with the participants.

On 12th Aug, an hour long motivation talk with the title of “Mismatch between Academia and Industry: Prepare Yourself to Fill Up THESE Gaps”, was delivered by Prof. Cheong Kuan Yew. It was participated by approximately seventy undergraduates from various local universities. The Speaker provided an overview of semiconductor and optoelectronic industries in Malaysia and elaborated the needs of green technology, nanotechnology, artificial intelligent (AI) and automation in assisting industrial revolution 4.0 to drive internet of things, big data analysis and storage via clouds. With the evolution in industries, huge challenges that may be encountered by future fresh graduates have been highlighted. In order for them to survive, essential survival skills that must be equipped to face the real world have been discussed.



Figure 3: Onsite Infineon factory visit which hosted by JS Sim (first squad down from right) from Infineon Technologies.



Figure 4: A good and interactive dialogue session about “Researchers@Work and “wefie” with all the participants at the end of the event.



Figure 5: Snap shot of Prof. Cheong’s movitation talk with the participants.

[IEMT 2018 Conference Kick-Off Meeting – August, 28th 2017](#)

(Compiled by Tan YY)

The IEMT 2018 conference organizing committee kick- off meeting was held on 28th August 2017 at one of the potential hotel options for the conference in Penang. The upcoming 2018 conference will be organized and sponsored by ITTT-CPMT Malaysia chapter as usual. Ms. Tan YY from Infineon will be the General Chair and Infineon will be the main Host. A team of energetic organizing committee with representatives from both the industry and academia have been voluntary accepted to contribute in various roles as table below. The conference is scheduled from September 4th - 6th, 2018. Stay tuned for further details and the 1st Call for Paper (CFP) that will be announced soon.

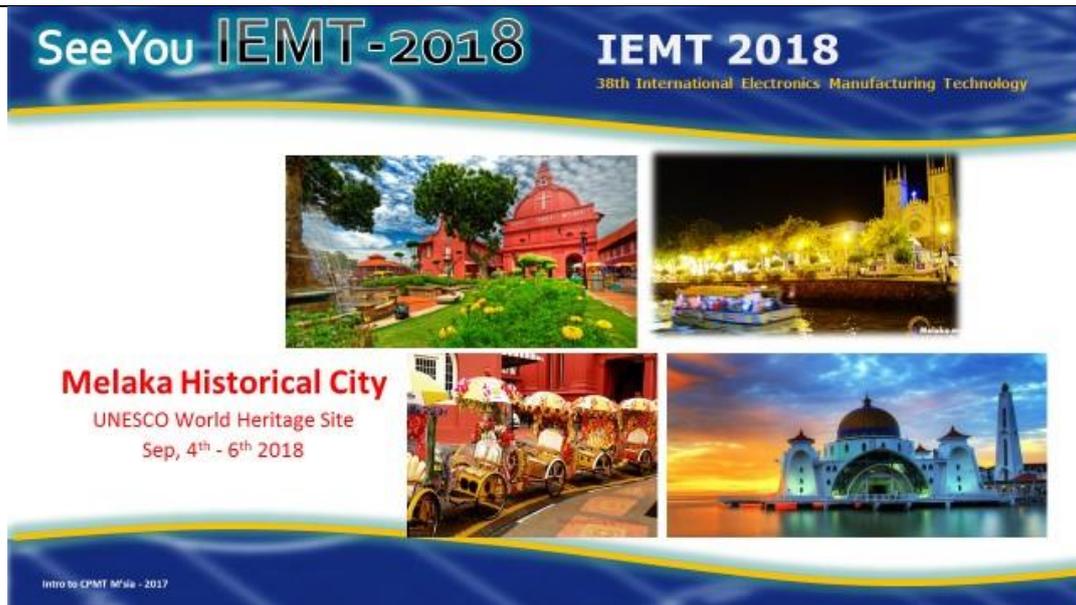


Figure 6: The participants of IEMT 2018 Conference Kick-off meeting



Table 1: The IEMT 2018 Organizing Committee

Advisor	Mr. Chew Chee Hiong	ON Semi
General Chair	Ms. Tan Yik Yee	Infineon
General Co-Chair	Mr. Wong Shaw Fong	Intel
Treasurer	Mr. Azhar Aripin	On Semi
Secretariat	Ms. Vaithilingam Paramesvari	Infineon
Program	Ms. Khor Swee Har	On Semi
	Mr. Keith Leow Eng Hoo	Intel
	Mr. Bernard	TactilisLtd
Publicity & Publication	Mr. Ng Chee Yang	Infineon
	Dr. Siow Kim Shyong	UKM
	Dr. Wong Yew Hoong	UM
Sponsor & Exhibition	Mr. Chai Chan Wah	Unisem
	Ms. Lily Khor	Carsem
	Mr. Ooi Eng-Lim	Atotech
Logistic & Social Tour	Mr. Jaafar Nor Azman	Infienon
	Mr. Kenneth Thum How Zhi	Indium
	Mr. Mdnazir MISLAN	ST
Technical Committee	Prof. Mohammad Nasir Tamin	UTM
	Porf. Cheong Kuan Yew	USM
	Dr. Chee Choong Kooi	Intel
	Mr. Lim Hoo Kooi	CREST
	Mr. Zal Aminullah	UTM
International Liaison	Dr. Eu Poh Leng	NXP
	Mr. Sim Jit Shen	Infineon
	Mr. Loke Mun Leong	Lumileds



2017 Semiconductor Advanced Packaging Workshop

(Compiled by Leow Eng Ho)

The IEEE CPMT Malaysia chapter has once again succeeded in its mission of constantly motivating local engineering community with technical knowledge sharing session from the internationally respected speakers. In year 2017, the team has fruitfully organized a 1-Day Semiconductor Advanced Packaging Workshop at Eastin Hotel, Penang and Sunway Resort Hotel, Kuala Lumpur scheduled respectively on September 26th and 27th. Approximately 120+ attendees- a diverse group of professionals from 30+ companies and local universities Malaysia wide, have gathered face-to-face in this bi-annual technical workshop at both venues.



Figure 7: Honorable speakers: Ms. E Jan Vardaman of TechSearch International Inc. (middle) & Mr. John Hunt of ASE (US) Inc. (right).

It's our honor to have invited semiconductor packaging industry's notable speakers, presenting two topics of interest: (1) Ms. E. Jan Vardaman (President, TechSearch International Inc.) on "Advanced Packaging Drivers: Smartphones, Big Data, and Automotive Electronics" (2) Mr. John Hunt (Senior Director, ASE (US) Inc.) on "Fan Out Packaging- Technology Overview and Evolution". They covered the introductory overview of advanced packaging technology trends, main market players and a prospective outlook on related future growth. Also, they discussed about the technology challenges and quality/reliability considerations span across package design and process domains.

In summary, this technical workshop was very informative, of all participants truly get inspired by the quality and quantity of late-breaking developments of emerging semiconductor packaging technologies. We would also like to thank CPMT HQ for the continued commitment and support of Distinguished Lecturer program. So, what's next? --38th International Electronics Manufacturing Technology (IEMT) 2018 Conference. We are looking forward to seeing you next year in Malacca!!



Figure 8: Attendees at Eastin Hotel, Penang



Figure 9: Attendees at Sunway Resort Hotel, Kuala Lumpur



Figure 10: Souvenir presentation to speakers as token of appreciation



Figure 11: Workshop-In-Progress and Networking hour

[18th International Conference on Electronic Packaging Technology \(ICEPT\)](#)

(Compiled by CH Chew)

CH represents Malaysia CPMT chapter to join 18th International Conference on Electronic Packaging Technology (ICEPT) for potential collaboration and benchmarking. This year, ICEPT has 500 delegates from 22 countries with > 370 papers covering nine special themes. The conference is hosted by Harbin Institute of Technology at the beautiful Sun Island Resort. It was attended by current CPMT president Jean Trehwella and ex CPMT president Dr Bill Chen and Dr Ricky Lee. CH presented a keynote entitled Innovations in Power Integrated Module. The Malaysia team received very warm hospitality from China Electronic Packaging team. Great Interactions With local academic team and warm support from professor Bike-Yun. Malaysia CPMT team also extend our Invitation to the great China team to participate in IEMT conference in the world heritage town of Melaka, Malaysia on 4-6 Sept, 2018. We hope the first meeting can spark more future collaborations between China and Malaysia CPMT/Packaging team.





Figure 12: The pictures taken during the ICEPT event

[19th International Conference on Electronics Materials and Packaging \(EMAP2017\)](#)

(Compiled by Shaw Fong Wong)

The “International Conference on Electronics Materials and Packaging (EMAP)” is a well-established APAC regional conference that promotes awareness of new advances in materials, design and simulations, fabrication, reliability, and thermal management of microsystem/MEMS packages, robot mechanisms and mechanical systems with electronic packaging application. The former eighteen conferences were very successfully hold in Singapore (1999), Hong Kong (2000, 2006, 2012), and Korea (2001, 2007), Taiwan (2002, 2008, 2014), Singapore (2003, 2010), Malaysia (2004, 2009, 2016), and USA (2015). This year, the 19th version of the EMAP2017 was again very successfully organized at Matsue-city, Shimane-pref., Japan, from September 25th to 28th 2017 under the leadership of General Chairperson, Prof. Dr. Mikio HORIE from Tokyo Institute of Technology, Japan. This conference is co-sponsored by JSME, JIEP, JSPE, and Laboratory for Materials and Structures (MSL) in Institute of Innovative Research, Tokyo Institute of Technology, Institute of Innovative Research (Tokyo Institute of Technology). Overall, it was great to have a good engagement from Malaysian delegates who represented by a few companies like ON Semiconductors, Lumileds and Intel Technology, that presented some selected papers and invited keynotes at this prestigious conference. Also, besides the technical knowledge exchange, the team enjoyed the good hospitalities and great Japanese food during the conference event. At the same time, Shaw Fong Wong also shared the “Call for Paper” for IEMT2018 that going to be hold at Malacca, Malaysia, with a very well-received from the EMAP2017 conference attendees. Arigato EMAP2017 and see you again soon in EMAP2018 at Hong Kong!



Figure 13: The group photos during banquet dinner and also steering committee meeting.



Figure 14: The Malaysian delegates and also Shaw Fong received a token of appreciation from Prof. Horie, the General Chair.

An Overview of Membership Reward Program:

(Compiled by: Dr Yew Hoong Wong)

IEEE-EPS (formerly known as IEEE-CPMT) Malaysia Chapter has recently launched Membership Reward Program to its loyal members. This is to appreciate and acknowledge members who have been provided support and engagement to the chapter and to encourage more IEEE-EPS Malaysia Chapter's membership. In order to obtain the latest particulars from the members, a Google Form has been created and disseminated. A special IEEE-EPS souvenir as membership reward will be delivered. Stay tuned!

Some Important References :

- Official IEEE website: <http://www.ieee.org>
- Official IEEE/EPS website (HQ): <https://eps.ieee.org/about.html>
- Official ECTC conference website: <http://www.businesswire.com/news/home/20170912005472/en>
- List of upcoming conferences : <https://eps.ieee.org/conferences.html>



Upcoming EPS Conferences & Meetings

Networking and constant knowledge advancement opportunities are always an important part of any conference. EPS chapters have lined up an outstanding program with top tier speakers and timely topics for 2017/2018. Below is a sampling. Mark the dates!

2017 12th International Microsystems, Packaging, Assembly and Circuits Technology Conference (IMPACT) Taipei, Taiwan	Oct 25, 2017 - Oct 27, 2017
2017 IEEE CPMT Symposium Japan (ICSJ) Kyoto, Japan	Nov 20, 2017 - Nov 22, 2017
2017 IEEE 19th Electronics Packaging Technology Conference (EPTC) Singapore	Dec 6, 2017 - Dec 9, 2017
2017 IEEE Electrical Design of Advanced Packaging and Systems Symposium (EDAPS) Hangzhou, China	Dec 14, 2017 - Dec 16, 2017
2018 19th International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE) Toulouse, France	Apr 15, 2018 - Apr 18, 2018
2018 IEEE 22nd Workshop on Signal and Power Integrity (SPI) Brest, France	May 22, 2018 - May 25, 2018
2018 17th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm) San Diego, CA USA	May 29, 2018 - Jun 1, 2018
2018 IEEE 68th Electronic Components and Technology Conference (ECTC) San Diego, CA USA	May 29, 2018 - Jun 1, 2018
2018 7th Electronic System-Integration Technology Conference (ESTC) Dresden, Germany Abstract Submission Date: Jan 31, 2018	Sep 18, 2018 - Sep 21, 2018
2018 IEEE Holm Conference on Electrical Contacts Albuquerque, NM USA Abstract Submission Date: Feb 5, 2018	Oct 14, 2018 - Oct 18, 2018

For more details on the upcoming conference list, kindly visit:

<https://eps.ieee.org/conferences.html>



[Electronic Components and Technology Conference](#)



Introduction



On behalf of the IEEE Electronic Components and Technology Conference (ECTC) Program Committee, it is my pleasure to invite you to submit an abstract for the 68th ECTC, to be held May 29 – June 1, 2018, at the Sheraton San Diego Hotel & Marina in San Diego, California, USA.

This premier international conference, sponsored by the IEEE Electronics Packaging Society (IEEE EPS, formerly the IEEE CPMT Society), covers a wide spectrum of electronic packaging technology topics, including components, materials, assembly, interconnect design, device and system packaging, wafer-level packaging, sensors and the Internet of Things (IoT), optoelectronics, silicon photonics, 2.5D and 3D integration technology, and reliability.

The ECTC Program Committee, with more than 200 experts from broad-ranging technical areas, is committed to creating an engaging technical program for all. ECTC typically attracts more than 1,400 attendees from over 25 countries. Last year's 67th ECTC in Orlando, Florida, had 1,439 attendees, with 337 papers and interactive presentations featured in 41 sessions. The 68th ECTC will continue with that tradition by being the premium venue to showcase all the latest developments in the electronic components industry where packaging has become a way to achieve device and system performance scaling.

The 68th ECTC program will include six parallel technical sessions in the mornings and afternoons over three days, along with other special topic panel discussions to present high-level trends and best practices in the industry. Professional Development Courses (PDCs) will also be offered by world-class experts, enabling participants to broaden their technical knowledge base.

The technical program and PDCs will be supplemented by Technology Corner Exhibits, which provide an opportunity for leading companies in the electronic components, materials, and packaging fields to exhibit their latest technologies and products. Last year's 67th ECTC featured a record number of 106 exhibitors.

As the Program Chair of the 68th ECTC, I invite you to submit an abstract between 250 and 750 words that describes the scope, content, and key points of your proposed technical paper at www.ectc.net. You are also welcome to submit proposals for PDCs. The deadline for abstract and proposal submission is October 9, 2017. Manuscripts conforming to the ECTC format are due by February 23, 2018, for inclusion in the Conference Proceedings. All abstracts and manuscripts must be original, free of commercial content, and non-confidential.

On behalf of the ECTC Program Committee, I look forward to seeing you at the Sheraton San Diego Hotel & Marina, San Diego, California, USA at the 68th ECTC, May 29 – June 1, 2018.

Chris Bower – 68th ECTC Program Chair
X-Celeprint, Inc., Research Triangle Park, North Carolina, USA

For more details on this conference, kindly visit : <http://www.ectc.net/index.cfm>